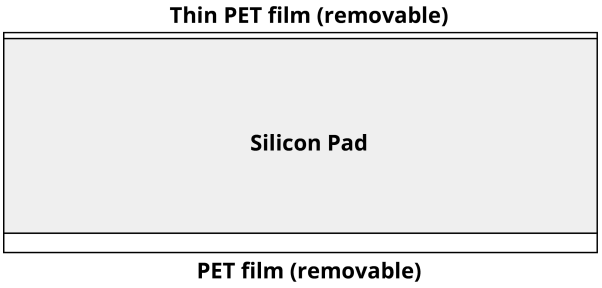
EC360 GOLD

Thermal Pad Series

The EC360® GOLD series presents the intermediate variant of high-performance thermal pads, which are on eye-level with premium thermal paste. The pads have an extraordinary thermal conductivity of 14.5 W/mK and are suitable for a variety of applications including CPUs and GPUs (that are cooled by thermal pads), memory chips and other electrical components. They perform particularly well for water cooling systems and are easy to use.

The pads are not adhesive, but stick a little, so they can be easily positioned. It is the perfect solution for heat-transfer in adverse surface conditions when the use of thermal paste is unsuitable. Handling is particularly safe, as the pads are electrically isolating and there is no risk of short-circuiting. Additionally, they can easily be cut using a scissor, which allows trimming to the perfect size for any surface.

Cross-section view



A full silicone pad covered with a PET film on both contact surfaces for increased stability and easy installation. Both are to be removed for installation.

Types and Configurations

Thickness*	Available sizes*
0.5 mm / 0.02 “	50x50 mm, 100x100 mm, 200x200 mm
1.0 mm / 0.04 “	50x50 mm, 100x100 mm, 200x200 mm
1.5 mm / 0.06 “	50x50 mm, 100x100 mm, 200x200 mm
2.0 mm / 0.08 “	50x50 mm, 100x100 mm, 200x200 mm

* Custom configurations are available upon request, for worldwide industrial inquiries please contact us at: sales@extremecool360.com

Technical Properties

Properties	Unit	Value	Test method
Color	-	red	Visual
Thermal Conductivity	W/mK	14.5	ASTM D5470
Specific Gravity	g / cm^3	2.6	ASTM D 792
Hardness	Shore C	40	ASTM D 2240
Elongation	kg/cm 2	55	ASTM D 412
	Pa	5.9×10^9	ASTM D 412
Volume Impedance	Ohm-cm	2.9×10^{11}	ASTM D 257
Breakdown Voltage	kV / mm	6,0	ASTM D 149
Usable Temperatures	°C	-40 - 220	EN 344
Flame Rating	-	VO	UL 94

Installation Recommendation

- Clean surfaces from dirt and other possible residue. If applicable, isopropyl 90% alcohol is recommended to ensure a clean surface.
- Remove one of the protective layers and place the exposed side of the thermal pad facing the surface of the chip. Once positioned gently press on it to make it stick. Remove the second protective layer and install the heatsink.

EC360 Extreme Cool Thermal Compounds